

FIG.1

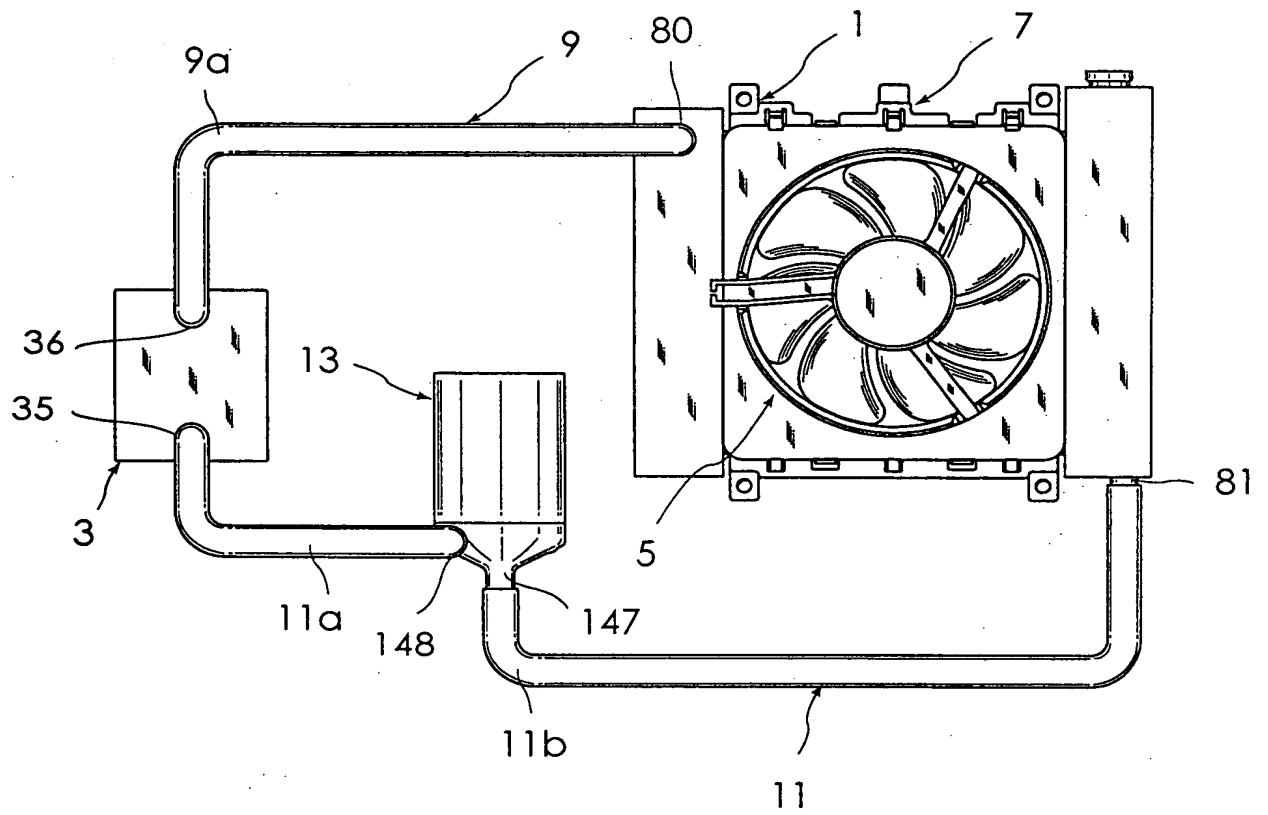


Fig. 1 is a schematic diagram of a rectangular device 3. The device contains a central region 32 with a grid of small rectangular elements. On the left and right sides, there are circular components 35 and 36, respectively. Arrows labeled "II C" point upwards from these components.

FIG. 1 is a perspective view of a first embodiment of a semiconductor device. The device consists of a rectangular substrate 3. On the bottom surface of the substrate, there is a thin layer 31. Two cylindrical components, labeled 35 and 36, are mounted on the top surface of the substrate. A label 31a points to the bottom surface of the substrate.

FIG.3A

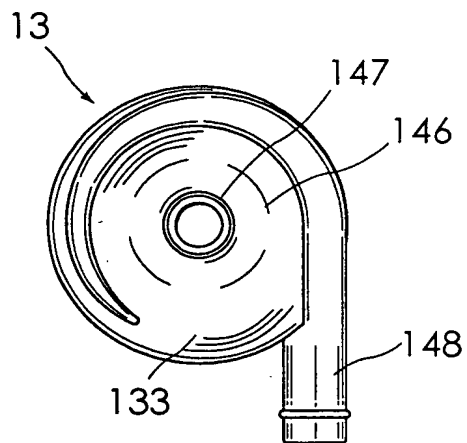


FIG.3B

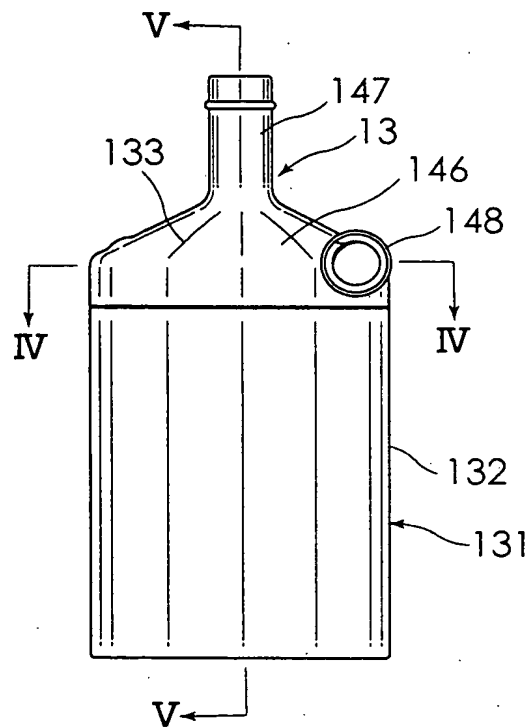


FIG.4

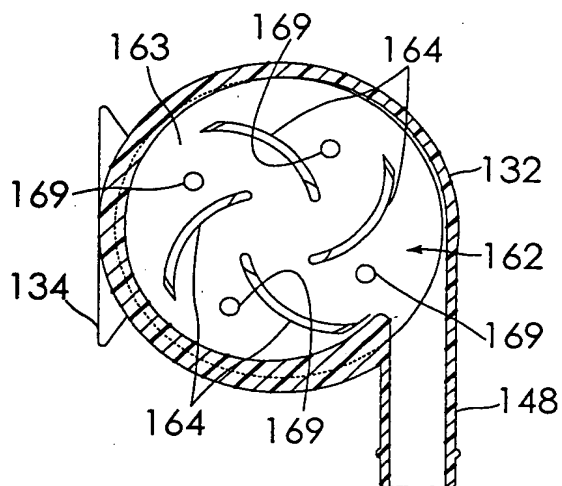


FIG.5

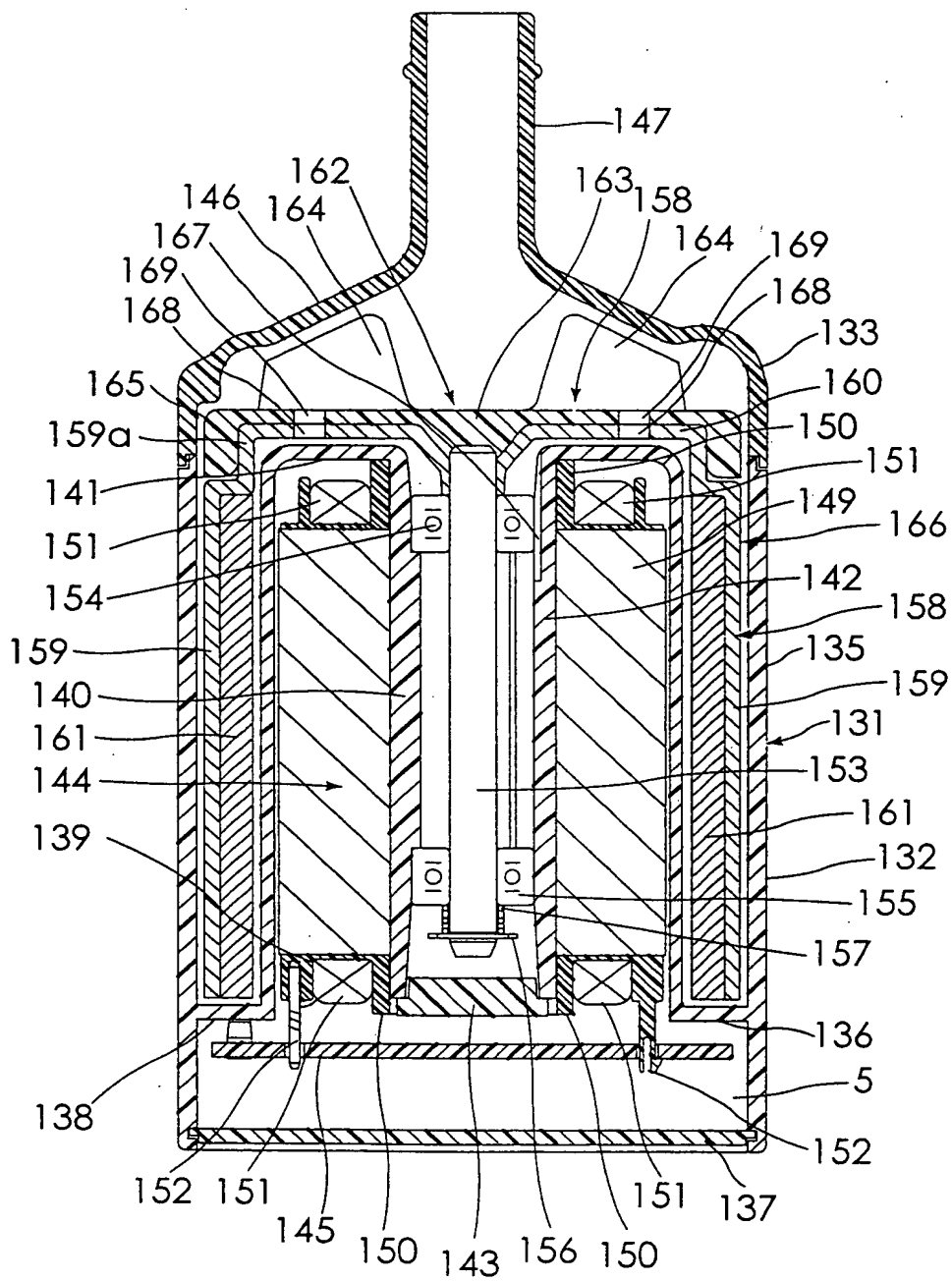


FIG.6A

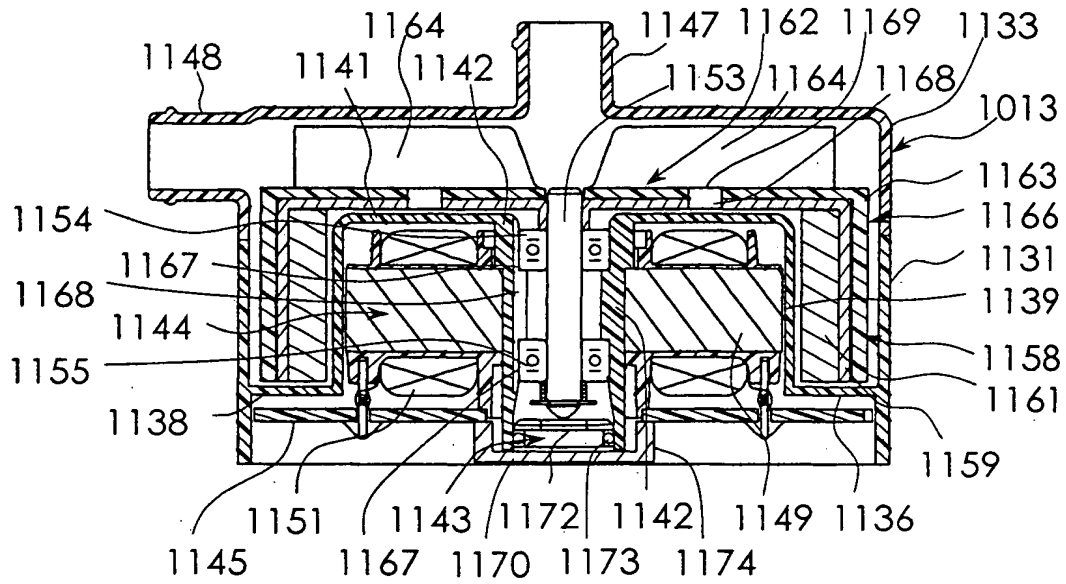


FIG.6B

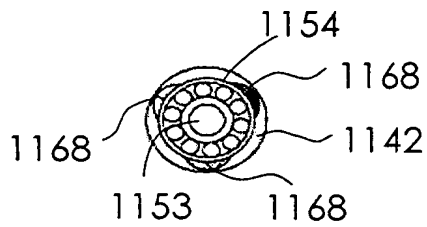


FIG.7

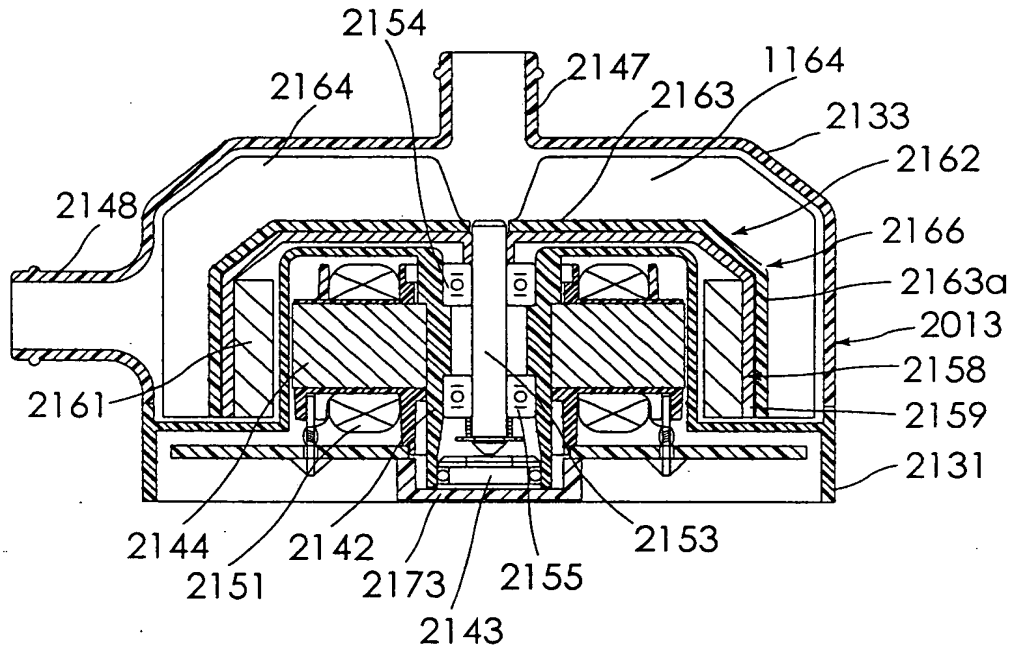


FIG.8A

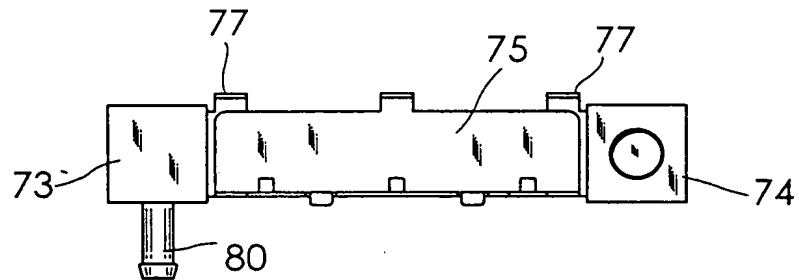


FIG.8C

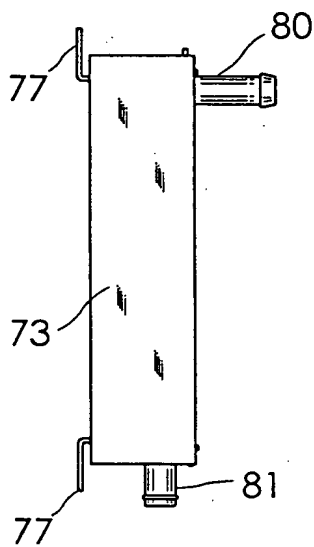


FIG.8B

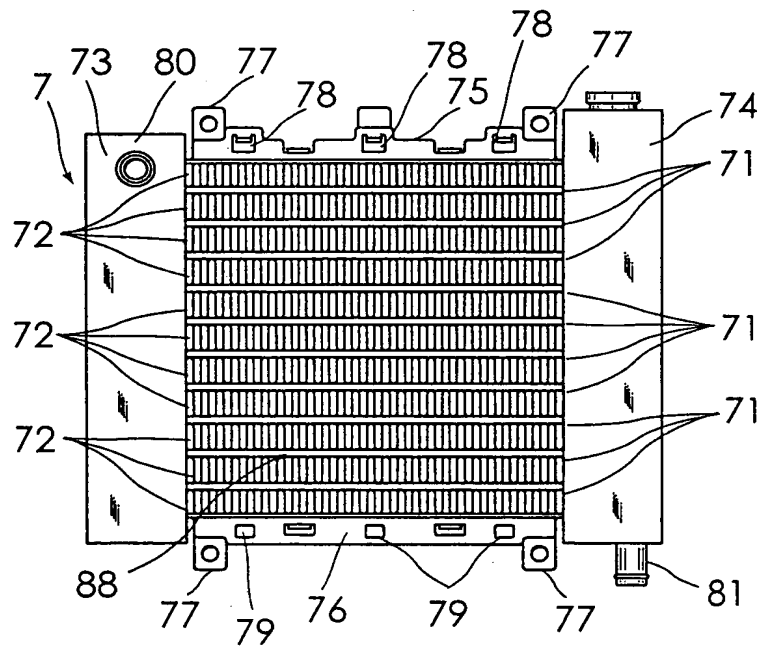


FIG.8D

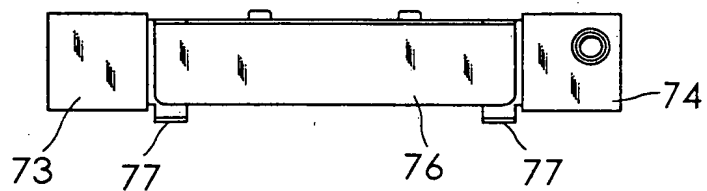




FIG. 9

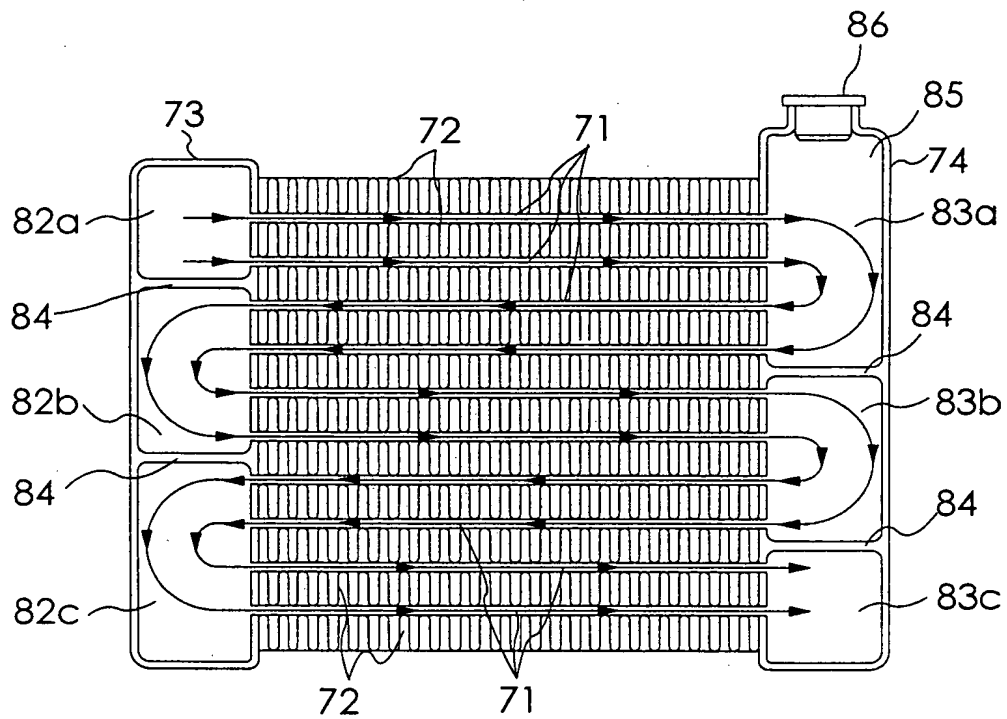


FIG.10

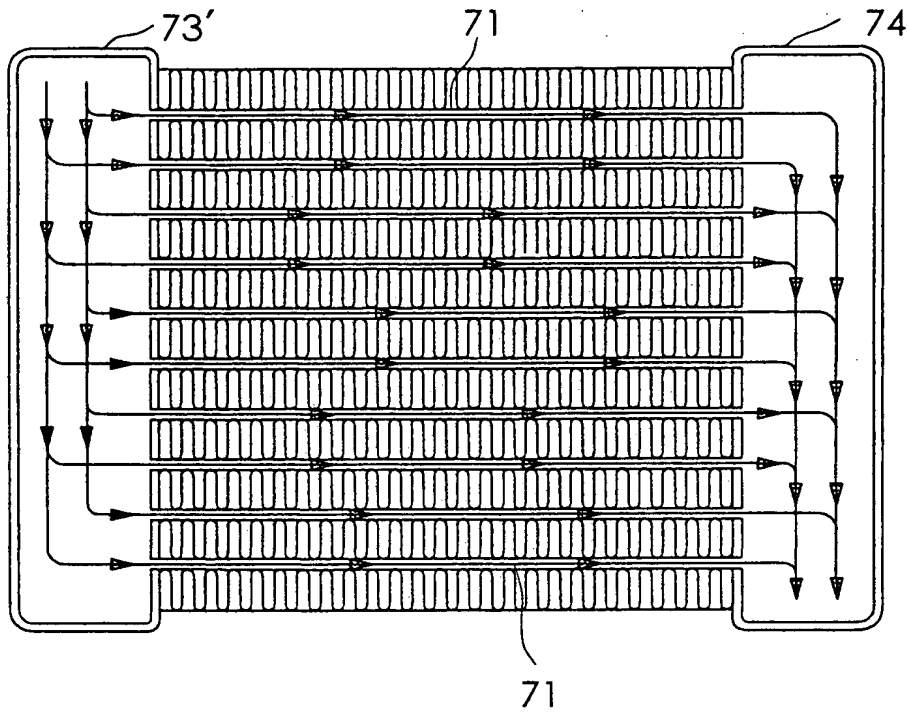


FIG.11

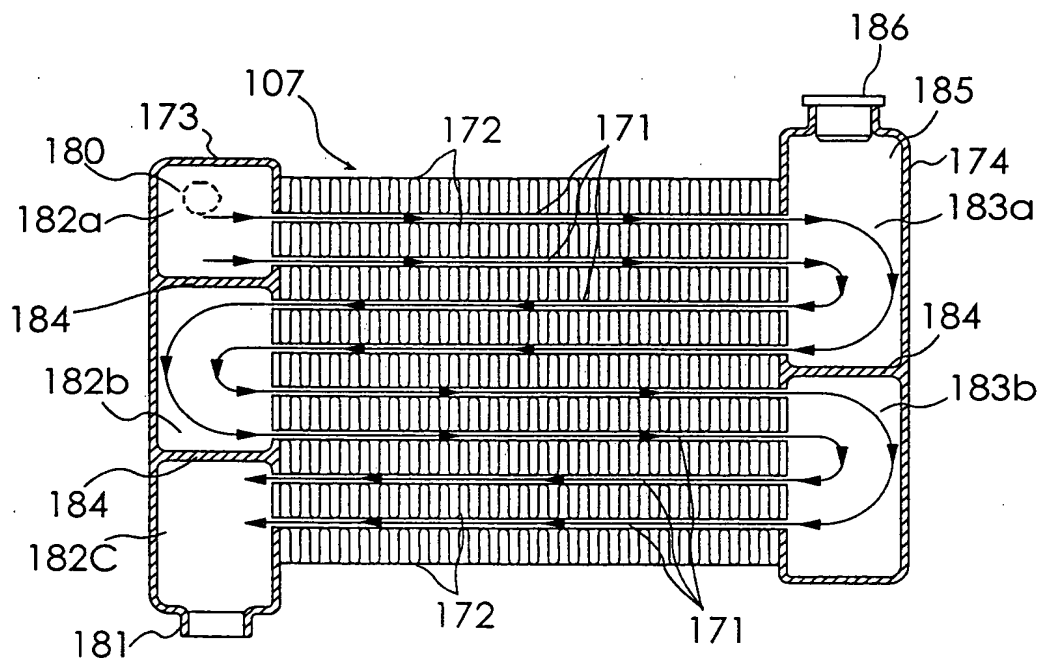


FIG.12C

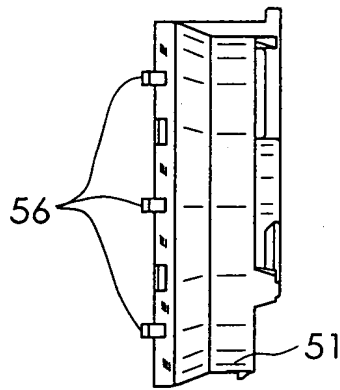


FIG.12A

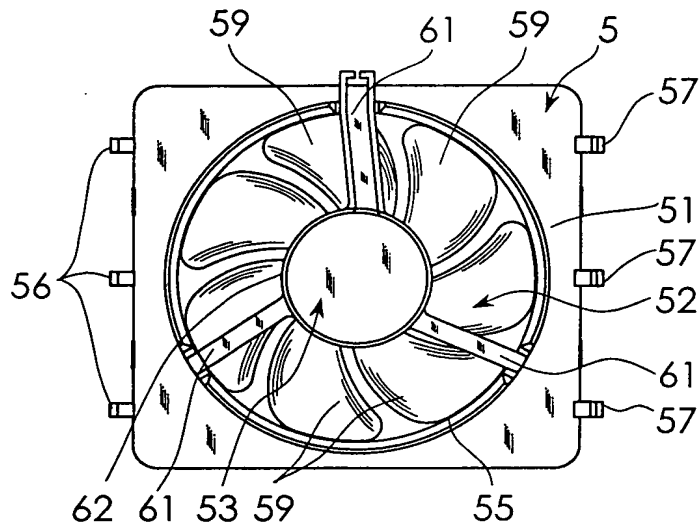


FIG.12B

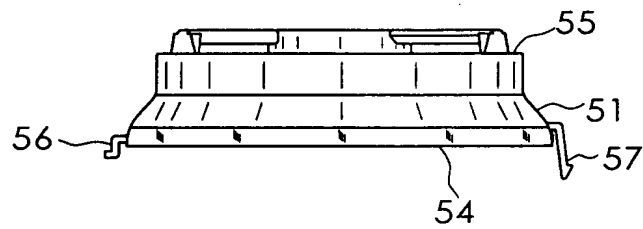


FIG.12D

